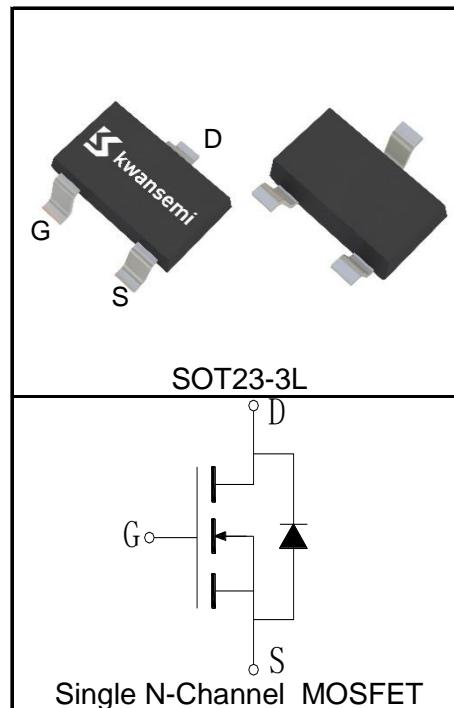


Features

- 60V/6.5A,
 $R_{DS(on)} = 16\text{m}\Omega$ (Typ.)@ $V_{GS}=10\text{V}$
- $R_{DS(on)} = 22\text{m}\Omega$ (Typ.)@ $V_{GS}=4.5\text{V}$
- Excellent $Q_G \times R_{DS(on)}$ product(FOM)
- SGT Gen2 Technology
- Low Capacitance to Minimize Driver Losses
- Fast Switching Speed

Pin Description



Applications

- Load Switch



Halogen-Free

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|--|---|------------------------|------------------|
| Common Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted) | | | |
| V_{DSS} | Drain-Source Voltage | 60 | V |
| V_{GSS} | Gate-Source Voltage | ± 20 | |
| T_{Jmax} | Maximum Junction Temperature | 150 | $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| I_S | Diode Continuous Forward Current | $T_A=25^\circ\text{C}$ | A |

Mounted on Large Heat Sink

| | | | | |
|-----------------------|---|------------------------|---------------------------|---|
| $I_{DP}^{(1)}$ | Pulse Drain Current | $T_A=25^\circ\text{C}$ | 26 | A |
| $I_D^{(2)}$ | Continuous Drain Current($V_{GS}=10\text{V}$) | $T_A=25^\circ\text{C}$ | 6.5 | A |
| | | $T_A=70^\circ\text{C}$ | 5.2 | |
| P_D | Maximum Power Dissipation | $T_A=25^\circ\text{C}$ | 1.25 | W |
| | | $T_A=70^\circ\text{C}$ | 0.8 | |
| $R_{\theta JL}$ | Thermal Resistance-Junction to Lead | 60 | $^\circ\text{C}/\text{W}$ | |
| $R_{\theta JA}^{(3)}$ | Thermal Resistance-Junction to Ambient | 100 | $^\circ\text{C}/\text{W}$ | |

Drain-Source Avalanche Ratings

| | | | |
|----------------|---------------------------------|----|----|
| $E_{AS}^{(4)}$ | Avalanche Energy, Single Pulsed | 12 | mJ |
|----------------|---------------------------------|----|----|

Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

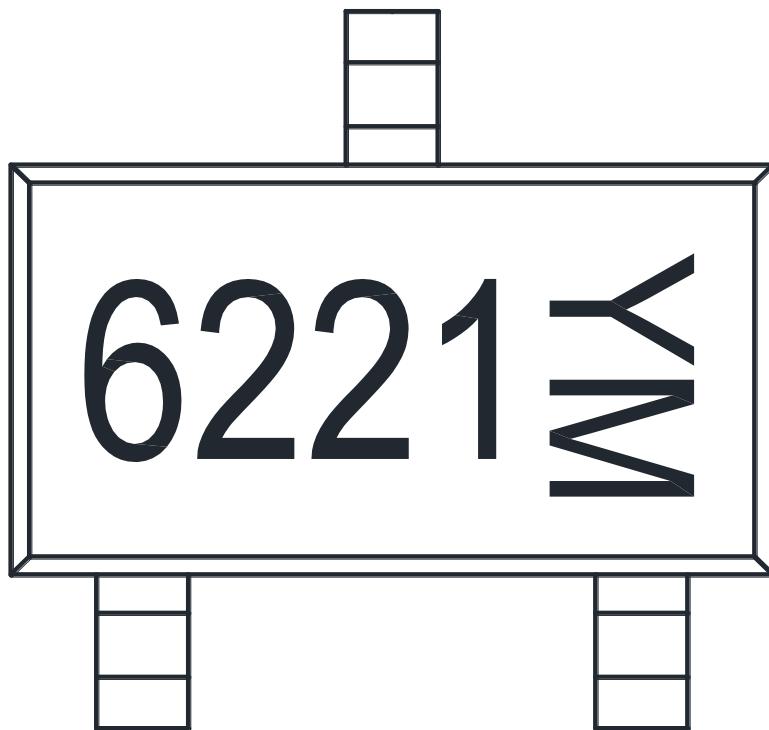
| Symbol | Parameter | Test Condition | Rating | | | Unit |
|---|----------------------------------|---|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Static Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _{DS} =250μA | 60 | 68 | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =60V, V _{GS} =0V | | | 1 | μA |
| | | T _J =125°C | | | 30 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _{DS} =250μA | 1.2 | 1.9 | 2.3 | V |
| I _{GSS} | Gate Leakage Current | V _{GS} =±20V, V _{DS} =0V | | | ±100 | nA |
| R _{DS(ON)} ^⑤ | Drain-Source On-state Resistance | V _{GS} =10V, I _{DS} =3A | | 16 | 19 | mΩ |
| | | V _{GS} =4.5V, I _{DS} =2A | | 22 | 28 | mΩ |
| Diode Characteristics | | | | | | |
| V _{SD} ^⑤ | Diode Forward Voltage | I _{SD} =3A, V _{GS} =0V | | 0.8 | 1.2 | V |
| t _{rr} | Reverse Recovery Time | I _{SD} =3A, dI _{SD} /dt=100A/μs | | 13 | | ns |
| Q _{rr} | Reverse Recovery Charge | | | 22 | | nC |
| Dynamic Characteristics ^⑥ | | | | | | |
| R _G | Gate Resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | | 4 | | Ω |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =30V, Frequency=1.0MHz | | 495 | | pF |
| C _{oss} | Output Capacitance | | | 210 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 8 | | |
| t _{d(ON)} | Turn-on Delay Time | V _{DD} =30V, I _{DS} =3A, V _{GEN} =10V, R _G =6Ω | | 6 | | ns |
| t _r | Turn-on Rise Time | | | 8 | | |
| t _{d(OFF)} | Turn-off Delay Time | | | 15 | | |
| t _f | Turn-off Fall Time | | | 9 | | |
| Gate Charge Characteristics ^⑥ | | | | | | |
| Q _g | Total Gate Charge | V _{DS} =30V, V _{GS} =10V, I _{DS} =3A | | 8.8 | | nC |
| Q _{gs} | Gate-Source Charge | | | 1.4 | | |
| Q _{gd} | Gate-Drain Charge | | | 2.1 | | |

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
- ④Limited by T_{Jmax}, Starting T_J = 25°C, I_{ASmax} = 7A, L=0.5mH, V_{DD} = 48V, R_G = 25Ω, V_{GS}=10V. Part not recommended for use above this value.
- ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

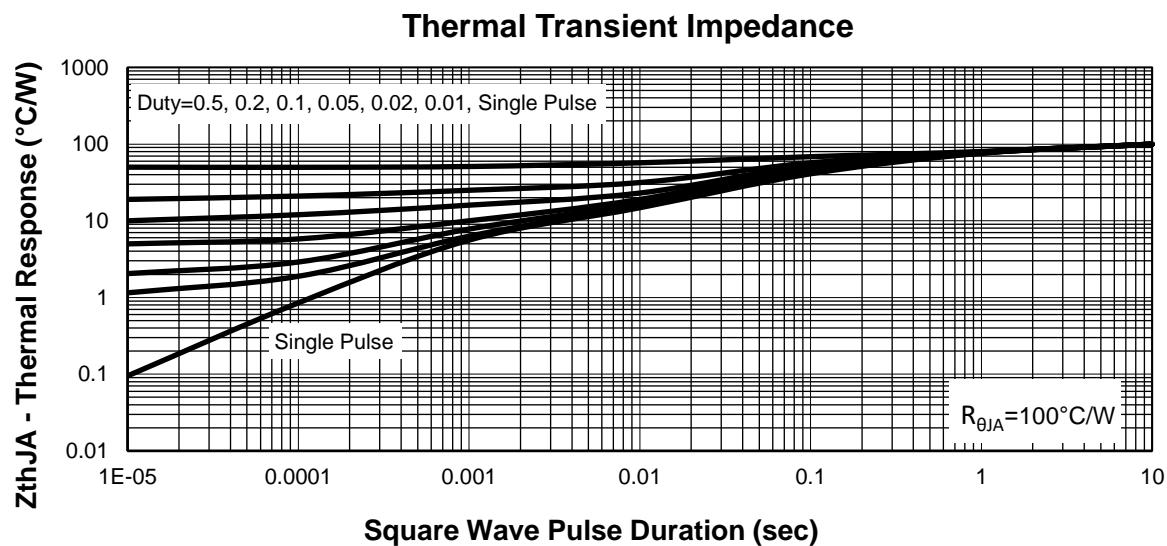
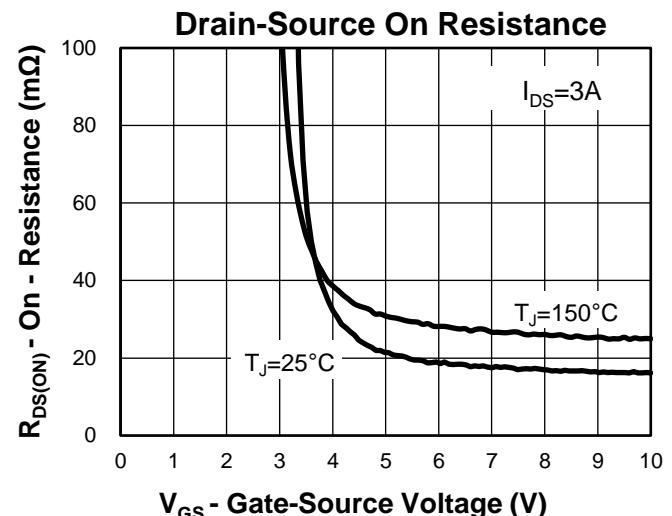
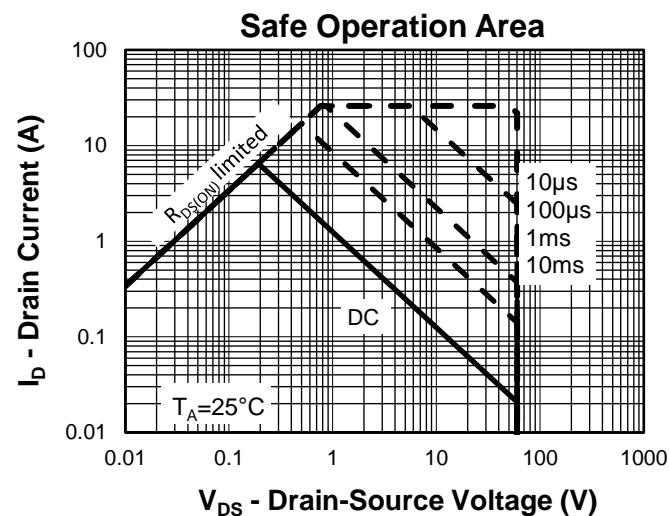
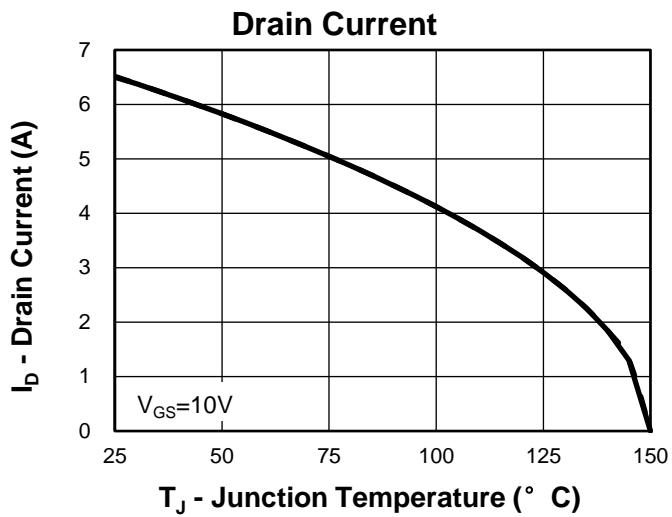
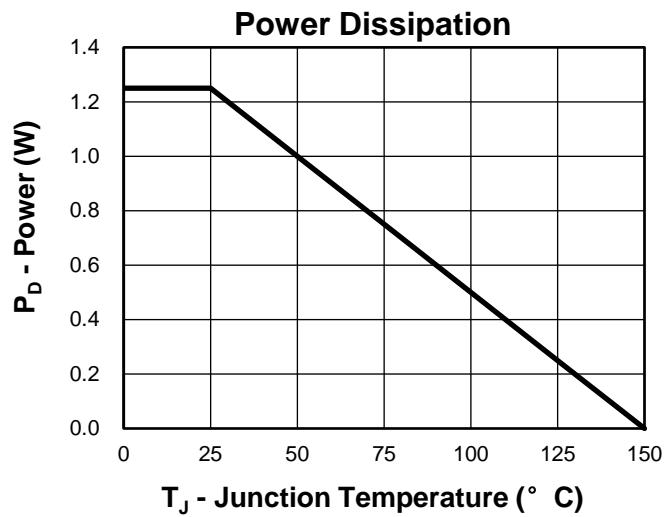
| Device | Package | Packaging | Quantity | Reel Size | Tape width |
|------------|----------|-----------|----------|-----------|------------|
| KS6221EAT2 | SOT23-3L | Tape&Reel | 3000 | 7" | 8mm |



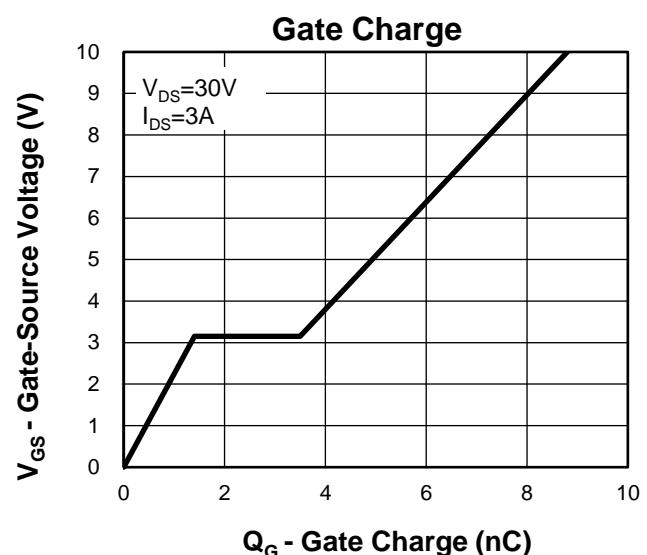
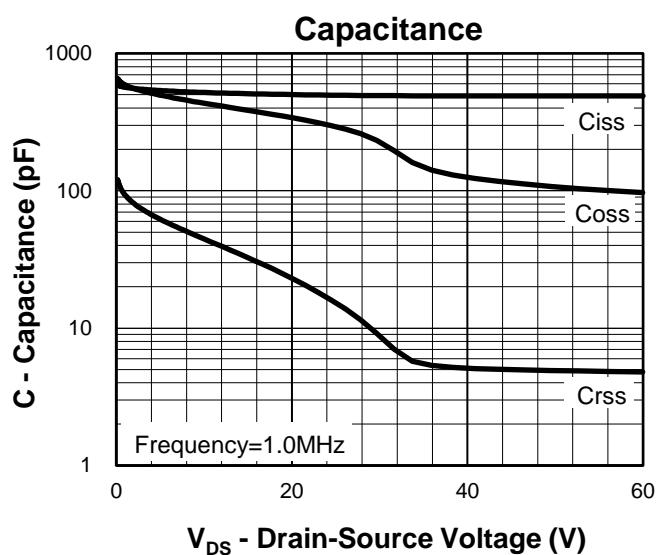
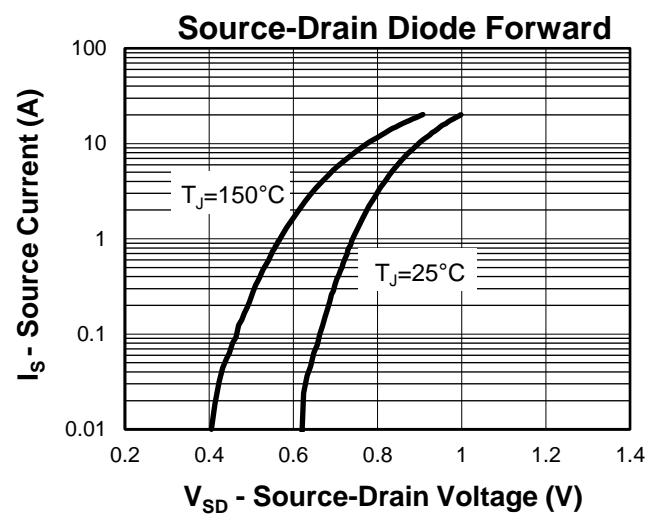
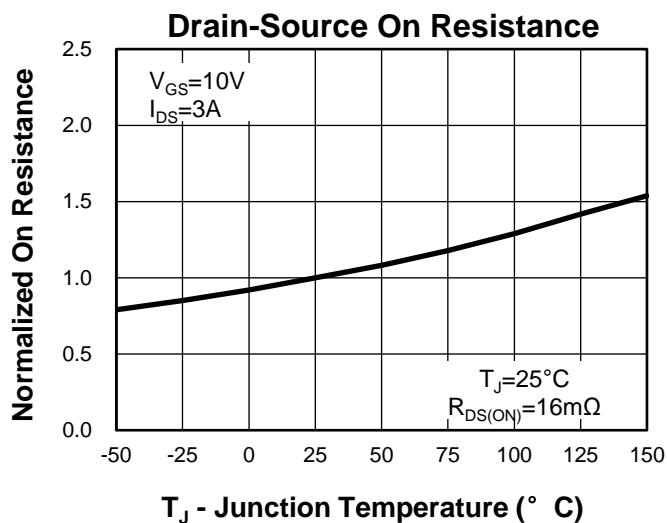
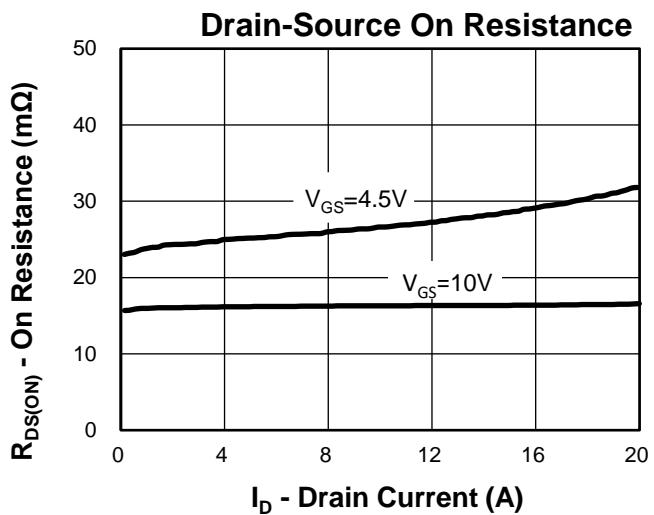
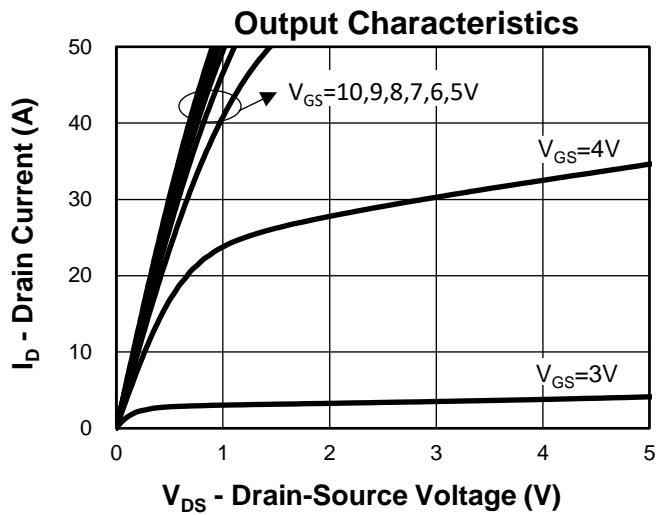
Y =Year,2017-A,2018-B,etc.

M =Month,Jan-1,Feb-2,...,Sep-9,Oct-A,Nov-B,Dec-C.

Typical Characteristics

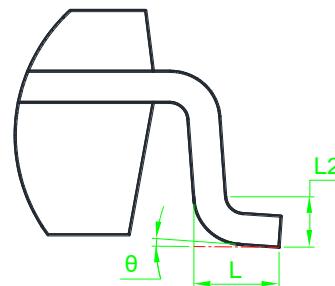
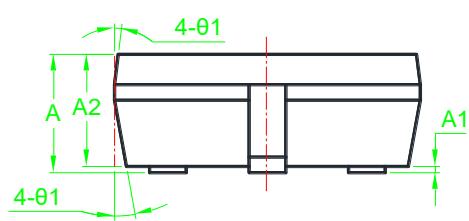
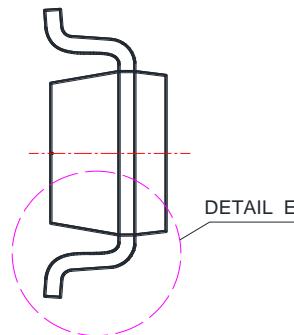
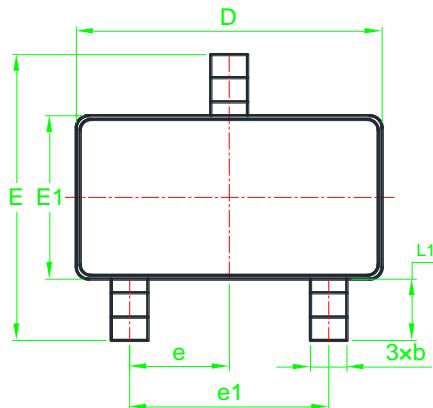


Typical Characteristics



Package Information

SOT23-3L



DETAIL E

| SYMBOL | MM | | | INCH | | | SYMBOL | MM | | | INCH | | |
|--------|------|------|------|-------|-------|-------|------------|----------|------|----------|-------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX | e | 0.95BSC | | 0.037BSC | | | |
| A | 1.05 | 1.15 | 1.25 | 0.041 | 0.045 | 0.049 | e | 0.95BSC | | 0.037BSC | | | |
| A1 | 0.01 | * | 0.10 | 0.000 | * | 0.004 | e1 | 1.9BSC | | 0.075BSC | | | |
| A2 | 1.05 | 1.10 | 1.15 | 0.041 | 0.043 | 0.045 | L | 0.30 | 0.45 | 0.60 | 0.012 | 0.018 | 0.024 |
| b | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 | L1 | 0.6REF | | 0.024REF | | | |
| D | 2.82 | 2.92 | 3.02 | 0.111 | 0.115 | 0.119 | L2 | 0.254BSC | | 0.01BSC | | | |
| E | 2.65 | 2.80 | 2.95 | 0.104 | 0.110 | 0.116 | θ | 0° | * | 8° | 0° | * | 8° |
| E1 | 1.50 | 1.60 | 1.70 | 0.059 | 0.063 | 0.067 | θ_1 | 0° | * | 10° | 0° | * | 10° |

Note: Dimensions do not include burrs and mold flash.

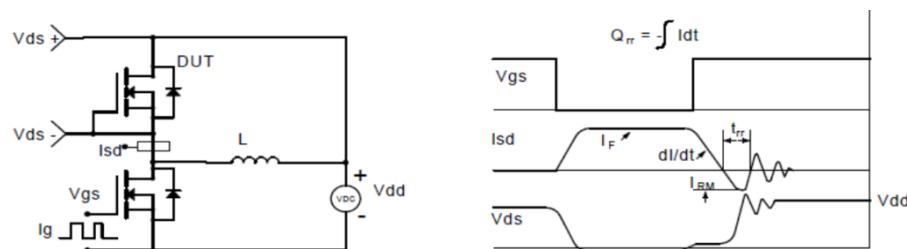
Avalanche Test Circuit and Waveforms



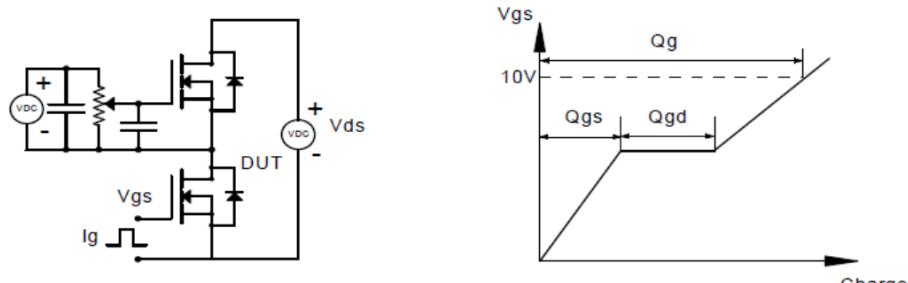
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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Web:www.kwansemi.com

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